

查询PEMD16_PUMD16供应商

PEMD16; PUMD16

NPN/PNP resistor-equipped transistors;
 $R1 = 22 \text{ k}\Omega$, $R2 = 47 \text{ k}\Omega$

Rev. 02 — 7 June 2005

Product data sheet

1. Product profile

1.1 General description

NPN/PNP resistor-equipped transistors.

Table 1: Product overview

Type number	Package		PNP/PNP complement	NPN/NPN complement
	Philips	JEITA		
PEMD16	SOT666	-	PEMB16	PEMH16
PUMD16	SOT363	SC-88	PUMB16	PUMH16

1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place cost

1.3 Applications

- Low current peripheral driver
- Control of IC inputs
- Replacement of general-purpose transistors in digital applications

1.4 Quick reference data

Table 2: Quick reference data

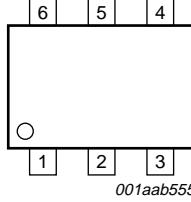
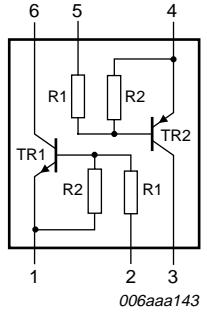
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	50	V
I_o	output current		-	-	100	mA
$R1$	bias resistor 1 (input)		15.4	22	28.6	$\text{k}\Omega$
$R2/R1$	bias resistor ratio		1.7	2.1	2.6	

PHILIPS

2. Pinning information

Table 3: Pinning

Pin	Description	Simplified outline	Symbol
1	GND (emitter) TR1		
2	input (base) TR1		
3	output (collector) TR2		
4	GND (emitter) TR2		
5	input (base) TR2		
6	output (collector) TR1		

3. Ordering information

Table 4: Ordering information

Type number	Package			Version
	Name	Description		
PEMD16	-	plastic surface mounted package; 6 leads		SOT666
PUMD16	SC-88	plastic surface mounted package; 6 leads		SOT363

4. Marking

Table 5: Marking codes

Type number	Marking code [1]
PEMD16	5H
PUMD16	D1*

- [1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
Per transistor; for the PNP transistor with negative polarity					
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	-	50	V
V _{EBO}	emitter-base voltage	open collector	-	5	V
V _I	input voltage TR1				
	positive		-	+40	V
	negative		-	-7	V
V _I	input voltage TR2				
	positive		-	+7	V
	negative		-	-40	V
I _O	output current		-	100	mA
I _{CM}	peak collector current		-	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT363	[1]	-	200	mW
	SOT666	[1] [2]	-	200	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C
Per device					
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT363	[1]	-	300	mW
	SOT666	[1] [2]	-	300	mW

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

6. Thermal characteristics

Table 7: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor						
R _{th(j-a)}	thermal resistance from junction to ambient	T _{amb} ≤ 25 °C				
	SOT363	[1]	-	-	625	K/W
	SOT666	[1] [2]	-	-	625	K/W
Per device						
R _{th(j-a)}	thermal resistance from junction to ambient	T _{amb} ≤ 25 °C				
	SOT363	[1]	-	-	416	K/W
	SOT666	[1] [2]	-	-	416	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

7. Characteristics

Table 8: Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Per transistor; for the PNP transistor with negative polarity						
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0 A	-	-	100	nA
I _{CEO}	collector-emitter cut-off current	V _{CE} = 30 V; I _B = 0 A	-	-	1	μA
		V _{CE} = 30 V; I _B = 0 A; T _j = 150 °C	-	-	50	μA
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	-	-	120	μA
h _{FE}	DC current gain	V _{CE} = 5 V; I _C = 5 mA	80	-	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	-	150	mV
V _{I(off)}	off-state input voltage	V _{CE} = 5 V; I _C = 100 μA	-	0.8	0.5	V
V _{I(on)}	on-state input voltage	V _{CE} = 0.3 V; I _C = 2 mA	2	1.1	-	V
R1	bias resistor 1 (input)		15.4	22	28.6	kΩ
R2/R1	bias resistor ratio		1.7	2.1	2.6	
C _c	collector capacitance	V _{CB} = -10 V; I _E = i _e = 0 A; f = 1 MHz	-	-	2.5	pF
	TR1 (NPN)		-	-	3	pF
	TR2 (PNP)		-	-		

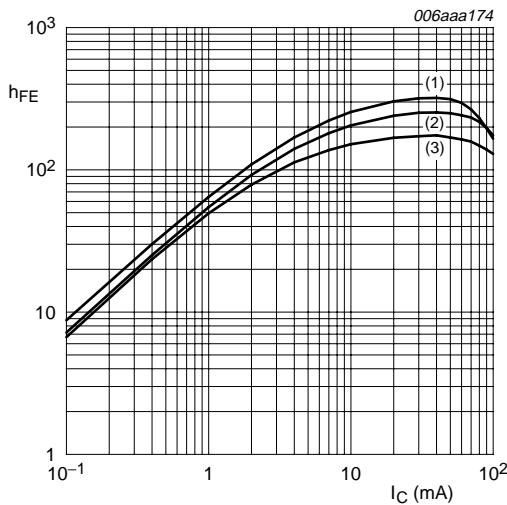


Fig 1. TR1 (NPN): DC current gain as a function of collector current; typical values

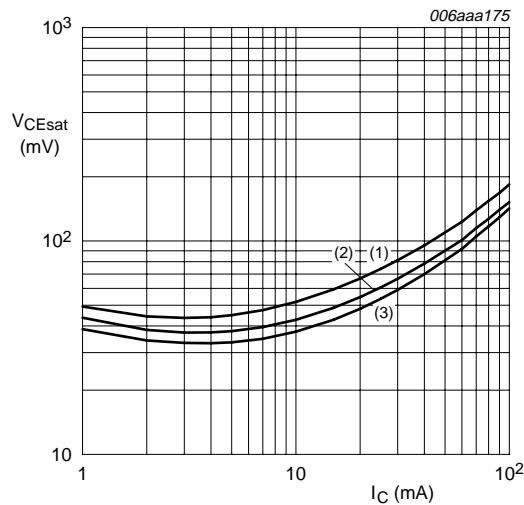


Fig 2. TR1 (NPN): Collector-emitter saturation voltage as a function of collector current; typical values

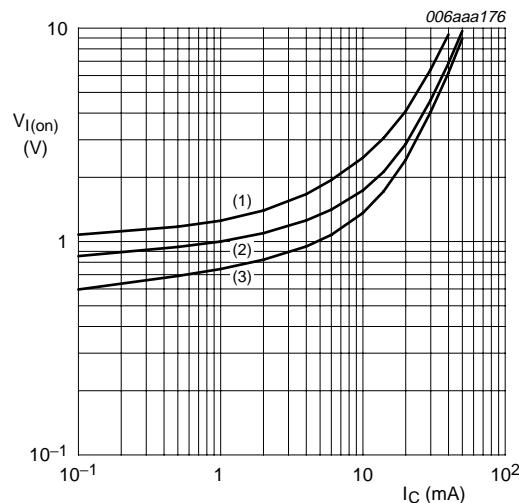


Fig 3. TR1 (NPN): On-state input voltage as a function of collector current; typical values

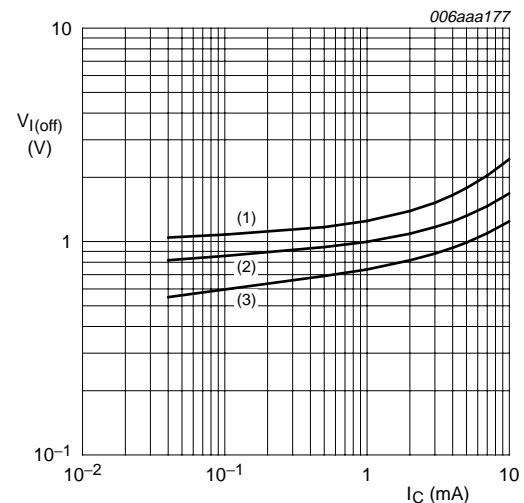
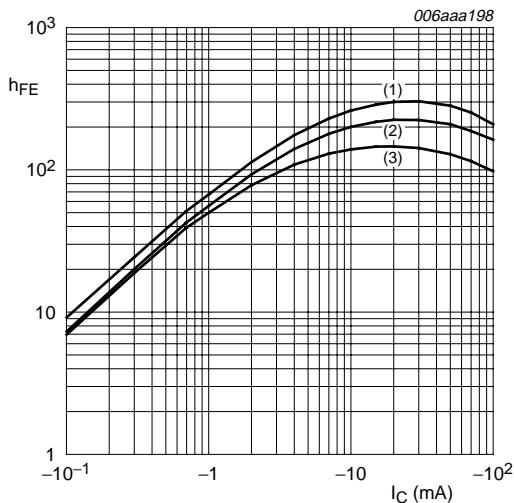
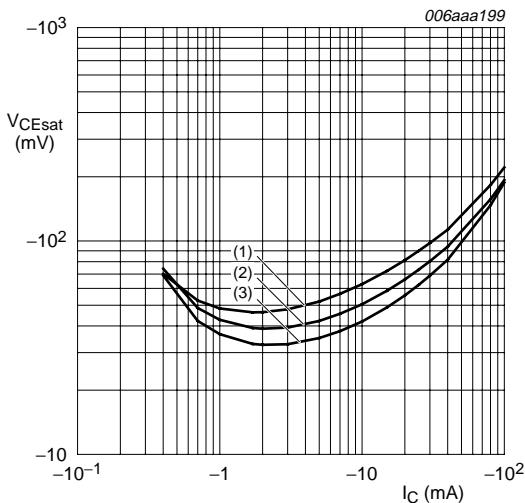


Fig 4. TR1 (NPN): Off-state input voltage as a function of collector current; typical values



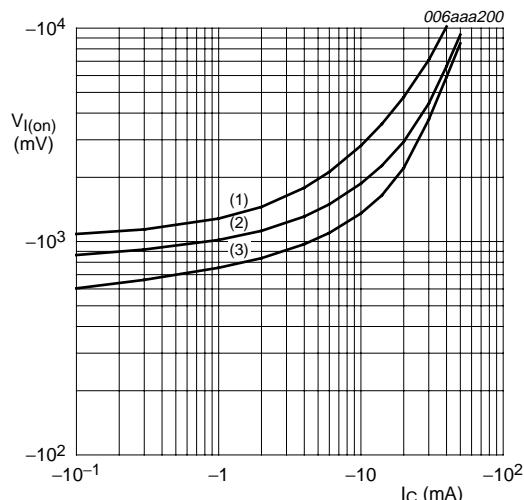
$V_{CE} = -5\text{ V}$
(1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 5. TR2 (PNP): DC current gain as a function of collector current; typical values



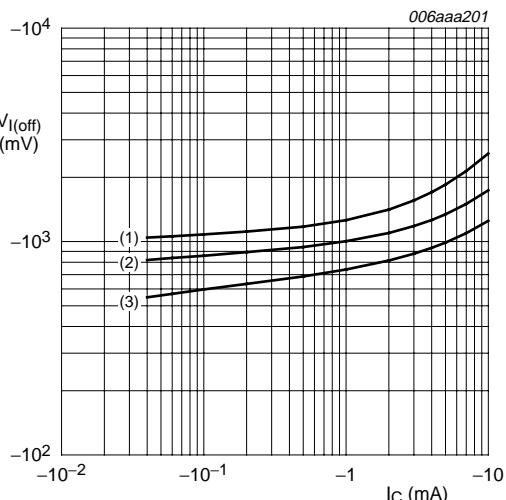
$I_C/I_B = 20$
(1) $T_{amb} = 100\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = -40\text{ }^{\circ}\text{C}$

Fig 6. TR2 (PNP): Collector-emitter saturation voltage as a function of collector current; typical values



$V_{CE} = -0.3\text{ V}$
(1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 7. TR2 (PNP): On-state input voltage as a function of collector current; typical values



$V_{CE} = -5\text{ V}$
(1) $T_{amb} = -40\text{ }^{\circ}\text{C}$
(2) $T_{amb} = 25\text{ }^{\circ}\text{C}$
(3) $T_{amb} = 100\text{ }^{\circ}\text{C}$

Fig 8. TR2 (PNP): Off-state input voltage as a function of collector current; typical values

8. Package outline

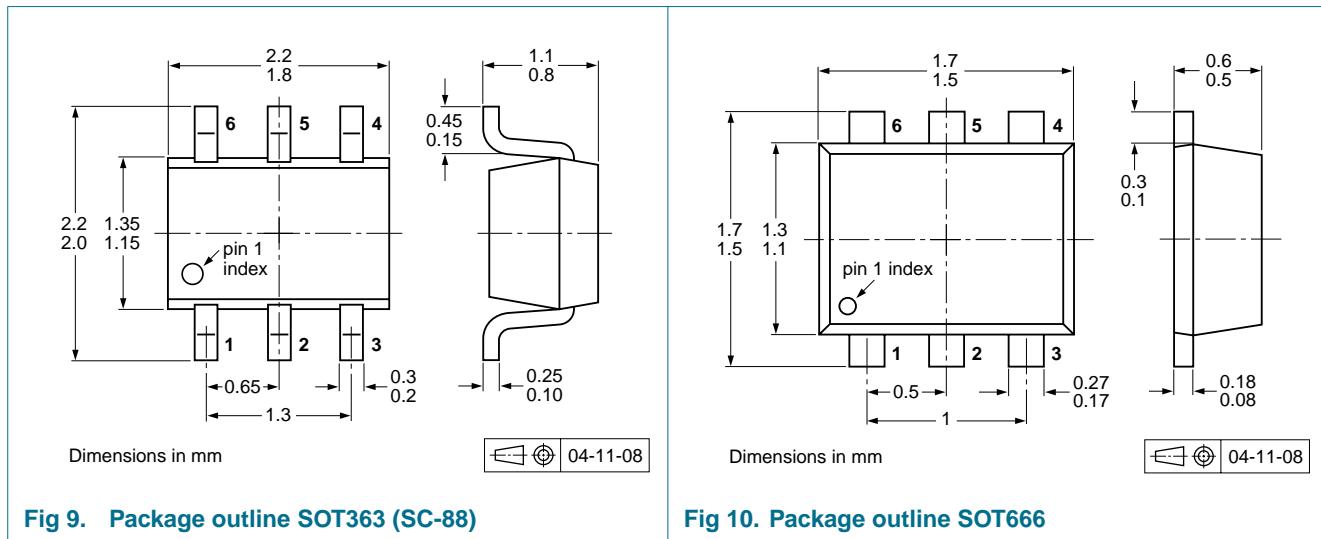


Fig 9. Package outline SOT363 (SC-88)

Fig 10. Package outline SOT666

9. Packing information

Table 9: Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code. [1]

Type number	Package	Description	Packing quantity		
			3000	4000	10000
PEMD16	SOT666	4 mm pitch, 8 mm tape and reel	-	-115	-
PUMD16	SOT363	4 mm pitch, 8 mm tape and reel; T1 [2]	-115	-	-135
		4 mm pitch, 8 mm tape and reel; T2 [3]	-125	-	-165

[1] For further information and the availability of packing methods, see [Section 15](#).

[2] T1: normal taping

[3] T2: reverse taping

10. Revision history

Table 10: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes	
PEMD16_PUMD16_2	20050607	Product data sheet	-	9397 750 15178	PUMD16_1	
Modifications:		<ul style="list-style-type: none">The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors.Type number PEMD16 addedTable 6 "Limiting values" V_{EBO} emitter-base voltage typing error adjustedTable 8 "Characteristics" $V_{i(on)}$ input-on voltage renamed to $V_{I(on)}$ on-state input voltageTable 8 "Characteristics" $V_{i(off)}$ input-off voltage renamed to $V_{I(off)}$ off-state input voltageFigure 1, 2, 3, 4, 5, 6, 7 and 8 electrical graphs for TR1 (NPN) and TR2 (PNP) addedTable 9 "Packing methods" added				
PUMD16_1	20031022	Product specification	-	9397 750 11865	-	



11. Data sheet status

Level	Data sheet status [1]	Product status [2][3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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